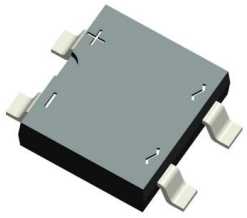
RMB2S
THRU
RMB6S

Technical Data
Data Sheet N1961, Rev. A

RMB2S-RMB6S Miniature Glass Passivated Fast Recovery Surface Mount Bridge Rectifiers

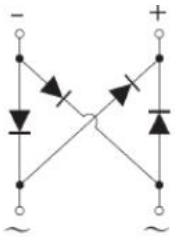


MB-S

Features

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed:260° C/ 10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability
- This is a Pb − Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: Molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbols marked on case
- Mounting Position: Any
- Weight: 0.0044 ounce, 0.126 grams

Maximum Ratings @T_A=25°C unless otherwise specified

Type number	Symbol	RMB2S	RMB4S	RMB6S	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM}	200	400	600	V
RMS Reverse Voltage	V_{RMS}	140	280	420	V
Maximum average forward current 60Hz sine save resistance load On glass-epoxy P.C.B. On aluminum substrate	$I_{F(AV)}$	0.5 0.8			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30			A

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Electrical Characteristics:

Type number	Symbol	RMB2S	RMB4S	RMB6S	Units
Maximum instantaneous forward voltage drop (Note 1)@ I_F = 0.4A	V_F	1.0			V
Maximum DC reverse current T_A = 25°C at rated DC blocking voltage T_A = 125°C	I_R	5 100			μA
Maximum reverse recovery time(Note 2)	trr	150			nS
Typical junction capacitance (per leg)	Cj	13			pF

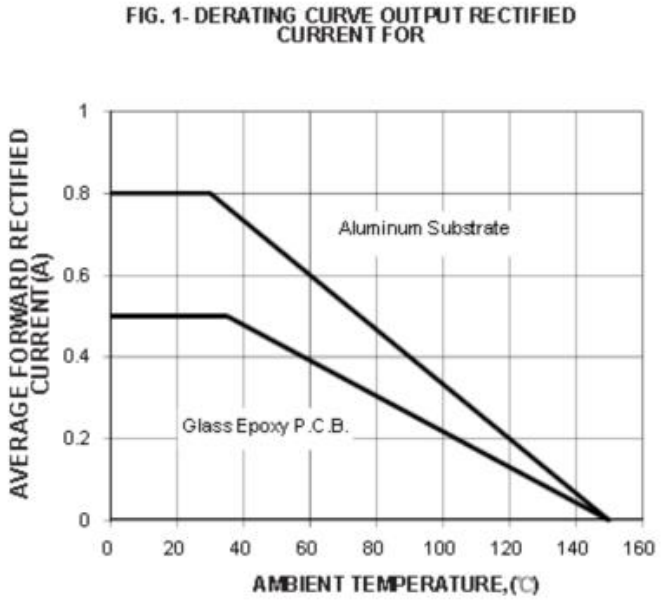
* Pulse width < 300 μs, duty cycle < 2%

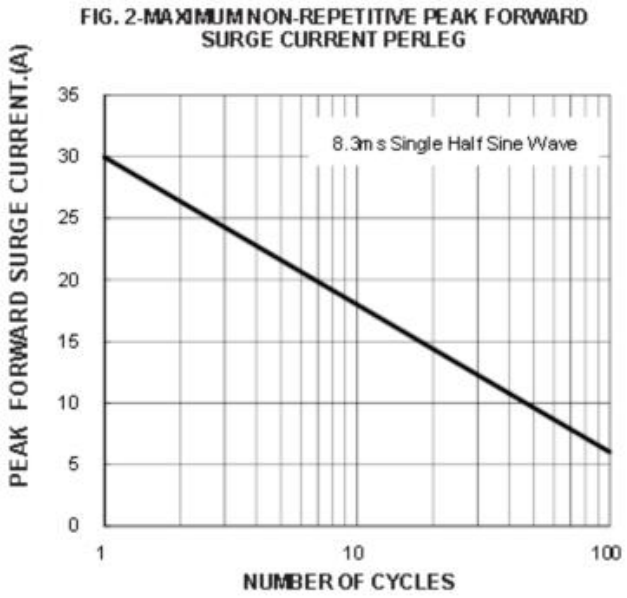
Thermal-Mechanical Specifications:

Type number	Symbol	RMB2S	RMB4S	RMB6S	Units
Typical thermal resistance	$R_{\theta JA}$	85			°C/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150			°C

Note: 1. Mounted on glass epoxy PC board with 1.3mm^2 solder pad..
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.
3. Thermal Resistance From Junction to Ambient

Ratings and Characteristics Curves





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RoHS

FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS PER LEG

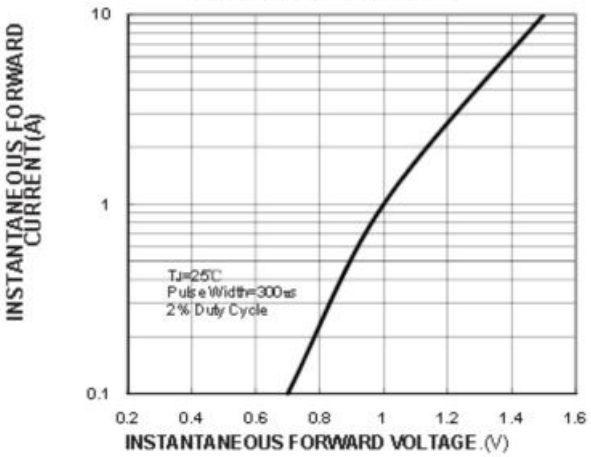


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS PER LEG

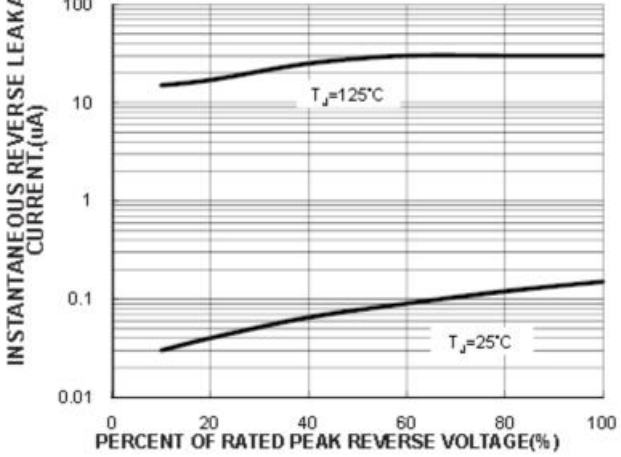
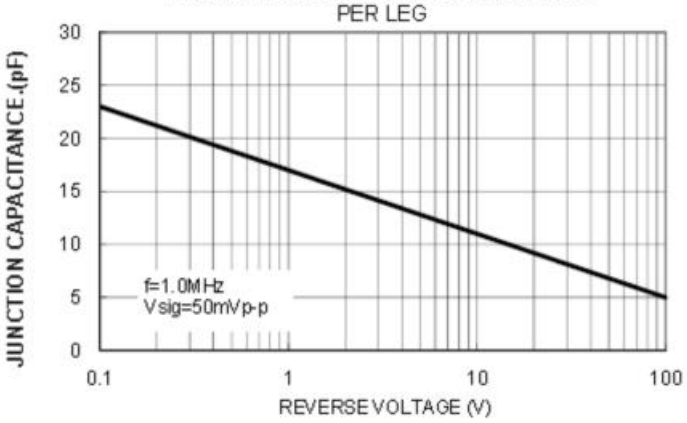


FIG. 5 TYPICAL JUNCTION CAPACITANCE PER LEG



Ordering Information

Device	Package	Shipping
RMB2S THRU RMB6S	MB-S (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram

Where XXXXX is YYWWL

RMB2S = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

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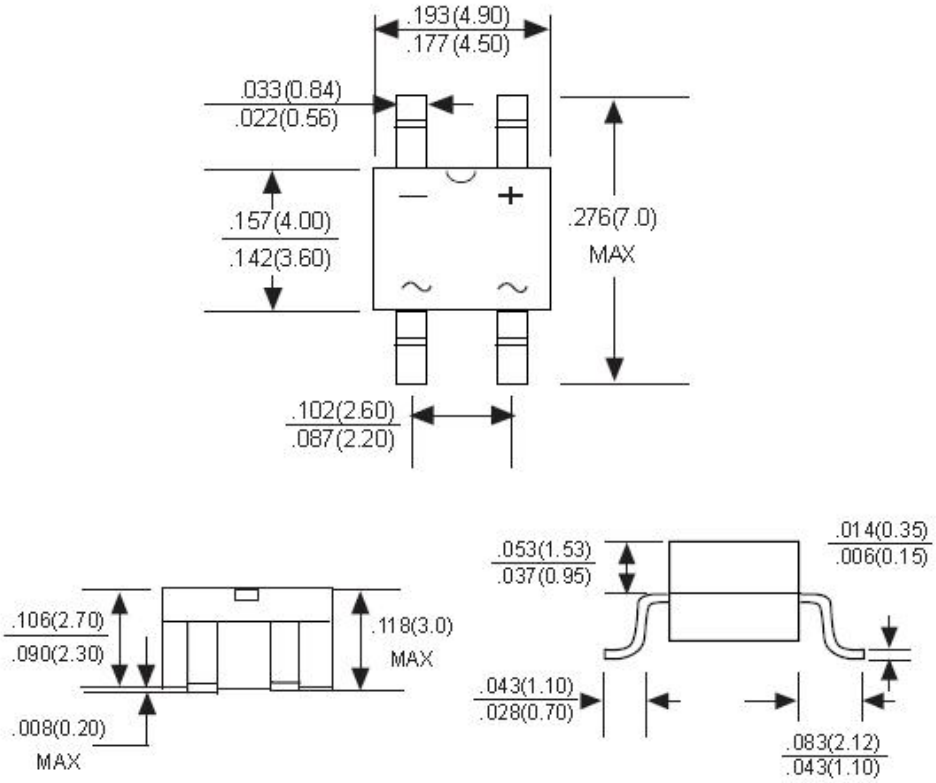
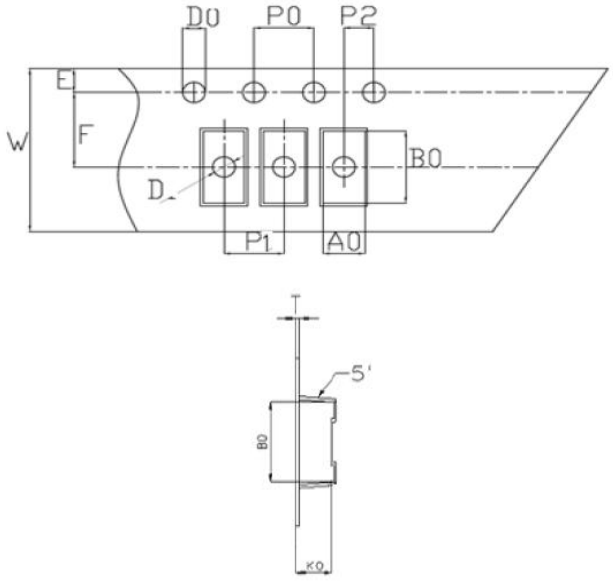
Mechanical Dimensions MB-S(Inches/Millimeters)



Carrier Tape Specification MB-S



SYMBOL	Millimeters	
	Min.	Max.
A0	4.92	5.12
B0	7.12	7.32
D0	1.50	1.60
D1	1.40	1.60
P0	3.90	4.10
P1	7.90	8.10
P2	1.95	2.05
E	1.65	1.85
K0	2.78	2.98
F	5.45	5.55
W	11.90	12.10
T	0.24	0.30
10P0	39.80	40.20
抗拉拉力	≥3KG	

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